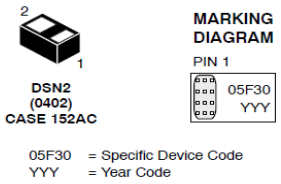
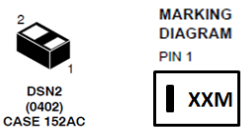
ON Semiconductor

Final Product/Process Change Notification

Document # : FPCN21451X
Issue Date: 13 September 2016

Title of Change:	Transfer of DSN2 Schottky plating site from existing external foundry facility to existing internal manufacturing site in Niigata, Japan.
Proposed first ship date:	20 December 2016 *or earlier upon customer approval*
Contact information:	Contact your local ON Semiconductor Sales Office or<masitah.aznam@onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office or<masitah.aznam@onsemi.com>
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or<masitah.aznam@onsemi.com>
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.
Change Part Identification:	Affected products from these changes with date code Dec 2016 and greater may be sourced from ON Niigata plating (Japan). Products from new sites will be identified through updated marking format as shown below. NSR05F30NXT5G **Existing marking**  05F30 = Specific Device Code YYY = Year Code NSR05F30NXT5G **New marking**  XX = Specific Device Code M = Date Code
Change category:	☐ Wafer Fab Change ☐ Assembly Change ☒ Test Change ☒ Other Plating Change

Change Sub-Category(s):

- ☒ Manufacturing Site Change/Addition
- ☐ Manufacturing Process Change
- ☐ Material Change
- ☐ Product specific change
- ☒ Datasheet/Product Doc change
- ☒ Shipping/Packaging/Marking
- ☐ Other: _____

Sites Affected:

- ☐ All site(s)
- ☐ not applicable
- ☒ ON Semiconductor site(s) : ON Niigata, Japan
- ☐ External Foundry/Subcon site(s) _____

Description and Purpose:

This Final Notification announces to customers of its plans to transfer of DSN2 Schottky plating site from existing external foundry facility to existing internal manufacturing site in Niigata, Japan.

ON Niigata facility is ON Semiconductor owned site that have been producing products for ON Semiconductor. Several existing technologies within ON Semiconductor's product families are currently sourced from both sites. ON Niigata is internal factory sites that are TS16949, ISO-9001 and ISO-14000 certified.

Qualification tests are designed to show that the reliability of the transferred devices will continue to meet or exceed ON Semiconductor standards.

Reliability Data Summary:

QV DEVICE NAME : NSR10F40NXT5G
PACKAGE: DSN2

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=90°C, 80% max rated V	1008 hrs	0/240
TC	JESD22-A104	Ta= -_40°C to +125°C	850cyc	0/240
H3TRB	JESD22-A101	85°C, 85% RH, 80%bias	1008 hrs	0/240
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/240

Electrical Characteristic Summary:
Three temperature characterization and ESD performance meet datasheet specification. Detail of Electrical characterization result is available upon request.

List of Affected Standard Parts:

Part Number	Qualification Vehicle
NSR02L30NXT5G	NSR02L30NXT5G
NSR02F30NXT5G	NSR02L30NXT5G
NSR05F40NXT5G	NSR10F40NXT5G
NSR10F20NXT5G	NSR10F40NXT5G
NSR10F30NXT5G	NSR10F40NXT5G

List of Affected Customer Specific Parts:

NOTE: Please be informed that parts impacted by this PDN/PCN are Special/Customer specific parts, thus MPN & CPN info will be available to affected customers only by clicking the "Custom PCN for Selected Company Button" in the Document Analysis page of PCMS/PCN Alert